



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20120907000
Add Cu wire as Alternative Wire Base Metal for select
BOAC devices on QFN package
Change Notification / Sample Request

Date: 9/27/2012
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN ww admin team@list.ti.com](mailto:PCN_admin_team@list.ti.com)).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20120907000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ24072TRGTT	null
BQ24075TRGTT	null
BQ24079RGTT	null
CDCE62002RHBT	null
TLC59401RHBT	null
TPS386000RGPT	null
TPS386040RGPT	null
TPS54060DRCT	null
TPS54240DRCT	null
TPS54260DRCT	null
TPS61040DRVR	null
TPS61252DSGT	null
TPS73701DRVT	null
TPS75105DSKT	null
UCC25230DRMT	null
UCC27200DRMR	null
UCC27200DRMT	null
UCC27201ADRMT	null
UCC27201DRMR	null
UCC27201DRMT	null
UCC27210DRMT	null
UCC27211DRMT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20120907000			PCN Date:	09/27/2012
Title:	Add Cu wire as Alternative Wire Base Metal for select BOAC devices on QFN package				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
Proposed 1st Ship Date:	12/27/2012		Estimated Sample Availability:	Date Provided at Sample request	
Change Type:					
☐ Assembly Site	☐ Assembly Process	☒ Assembly Materials			
☐ Design	☐ Electrical Specification	☐ Mechanical Specification			
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and there will be no other piece part changes.					
Reason for Change:					
Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
None					
Product Affected:					
BQ24072TRGTR	TLC59401RHBT	TPS61185RGER	UCC25230DRMT		
BQ24072TRGTT	TPS386000RGPR	TPS61185RGET	UCC27200ADRM		
BQ24075TRGTR	TPS386000RGPT	TPS61252DSGR	UCC27200ADRMT		
BQ24075TRGTT	TPS386020RGPR	TPS61252DSGT	UCC27200DRMR		
BQ24079RGTR	TPS386020RGPT	TPS62404DRCR	UCC27200DRMRG4		
BQ24079RGTT	TPS386040RGPR	TPS62404DRCT	UCC27200DRMT		
BQ24079TRGTR	TPS386040RGPT	TPS650231RSBR	UCC27200DRMTG4		
BQ24079TRGTT	TPS386060RGPR	TPS650231RSBT	UCC27201ADRM		
BQ24351DSGR	TPS386060RGPT	TPS65023BRSBR	UCC27201ADRMT		
BQ24351DSGT	TPS51311RGTR	TPS65023BRSBT	UCC27201DRMR		
CDCE62002RHBR	TPS54060DRCR	TPS65148CRHBR	UCC27201DRMRG4		
CDCE62002RHBT	TPS54060DRCT	TPS65552ARGTR	UCC27201DRMT		
HPA00810-1/2	TPS54240DRCR	TPS65552ARGTRE3	UCC27201DRMTG4		
SN0901059BRSBR	TPS54240DRCT	TPS65573DSSR	UCC27210DRMR		
SN0901059BRSBT	TPS54260DRCR	TPS65573DSST	UCC27210DRMT		
SN0907042RGER	TPS54260DRCT	TPS73701DRVR	UCC27211DRMR		
SN0910017DSGR	TPS61040DRVR	TPS73701DRV	UCC27211DRMT		
SN0910017DSGT	TPS61040DRVRG4	TPS75105DSKR	UCD7230ARGWR		
SN1007054RTER	TPS61040DRV	TPS75105DSKT	UCD7230ARGWT		
TLC59401RHBR	TPS61040DRV	UCC25230DRMR			

Qualification Data Approved (09/18/2012)

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1 : TPA6201A1DRBR (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR-CARSEM	Mold Compound:	435370
# Pins-Designator, Family:	8-DRB, VSON	Mount Compound:	439525
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Cu

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size (Pass/Fail)
X-ray	(Top Side Only)	5/0
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	15/0
Notes ** - Preconditioning sequence: Level 2-260C.		

Qual Vehicle 2 : TPS62046DRCR (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR-CARSEM	Mold Compound:	435370
# Pins-Designator, Family:	10-DRC, VSON	Mount Compound:	439525
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Cu

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	FT Data log comparison against BL	30/0	30/0	30/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	72/0	72/0	72/0
**High Temp. Storage Bake	150C (1000 hrs)	77/0	77/0	77/0
X-ray	(Top Side Only)	5/0	5/0	5/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
Notes ** - Preconditioning sequence: Level 2-260C.				

Qual Vehicle 3 : TPS62410DRCR (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR-CARSEM	Mold Compound:	435370
# Pins-Designator, Family:	10-DRC, VSON	Mount Compound:	439525
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., Cu

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	150C (1000 hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
X-ray	(Top Side Only)	5/0	5/0	5/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes ** - Preconditioning sequence: Level 2-260C.				

Qual Vehicle 4 : TPS65167ARHAR (MSL 2-260C)				
Package Construction Details				
Assembly Site:	CAR-CARSEM	Mold Compound:	435370	
# Pins-Designator, Family:	40-RHA, VQFN	Mount Compound:	439525	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., Cu	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size (Pass/Fail)		
Electrical Characterization	FT Data log comparison against BL	30/0		
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0		
X-ray	(Top Side Only)	5/0		
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0		
Notes ** - Preconditioning sequence: Level 2-260C.				
Qual Vehicle 5 : TPS74801DRCR (MSL 2-260C)				
Package Construction Details				
Assembly Site:	CAR-CARSEM	Mold Compound:	435370	
# Pins-Designator, Family:	10-DRC, VSON	Mount Compound:	439525	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	2.0 Mil Dia., Cu	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot# 1	Lot#2	Lot#3
Electrical Characterization	FT Data log comparison against BL	30/0	30/0	30/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**High Temp. Storage Bake	150C (1000 hrs)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
Notes ** - Preconditioning sequence: Level 2-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com